

下列条件适用于 SMD 产品系列内的所有零件：

- 请参照技术手册中的建议设计电路板。
- 必须根据回流焊/波峰焊技术规范选择合格的焊料，严格控制焊接温度、时间。
- 焊接工艺会导致产品表面变色。
- 爬锡现象会导致内孔堵塞，因此通孔产品不适用波峰焊，建议采用回流焊。
- 所有产品应在出厂 12 个月内使用，超出有效期会影响可焊性。
- 必须在密封、干燥环境下保存。
- 零件与 PCB 的连接强度由产品、焊盘、焊接效果等因素综合决定
- 必须控制最大锁附扭力，防止元件和 PCB 受到机械破坏。
- 工作电流由 PCB、电缆接头、电缆横截面等因素综合决定。
- 手册中如有标注参考电流，零件使用材料为黄铜 C3604(H59)

Cautions and Warnings:

The following conditions apply to all goods within the product series of yiyuan PCB SMD

General:

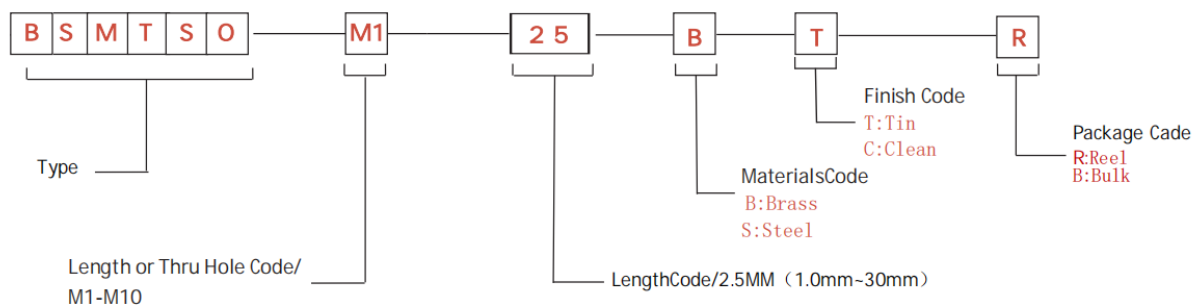
All recommendations according to the general technical specifications of the data-sheet have to be complied with.

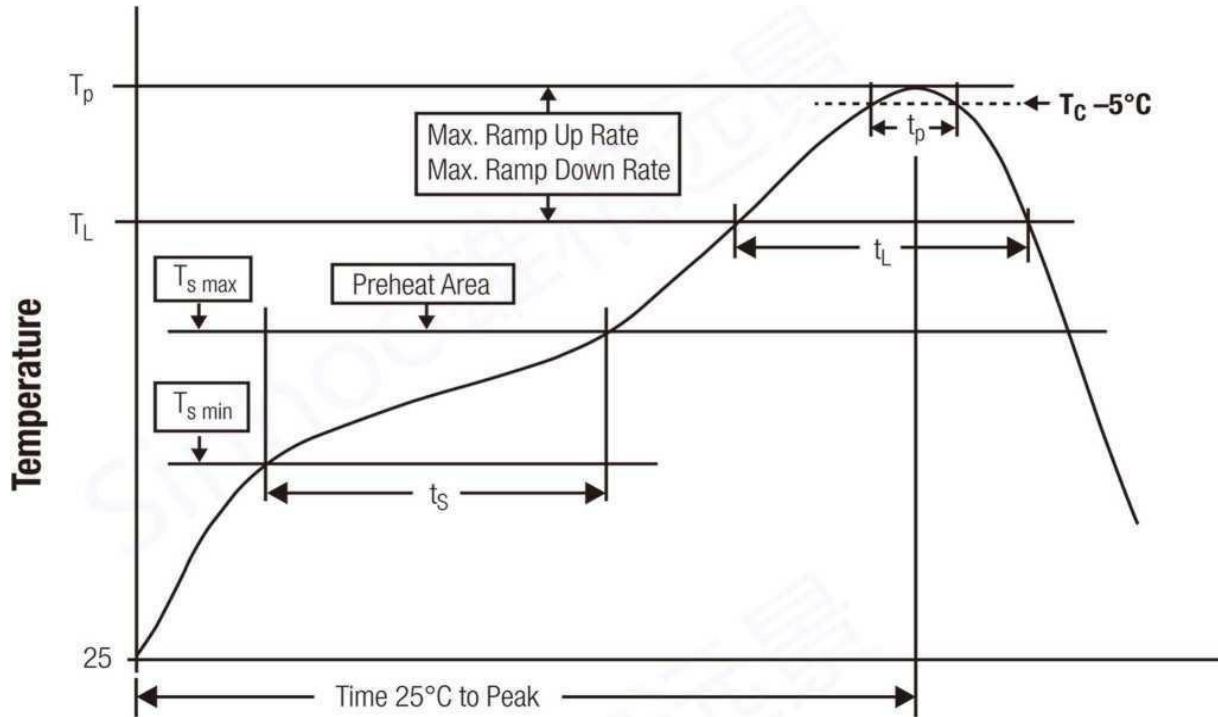
The responsibility for the applicability of customer specific products and use in a particular customer design is always within the authority of the customer. All technical specifications for standard products do also apply for customer specific products.

Product Specific:

Follow all instructions in the datasheet, especially:

- The solder profile has to be complied with according to the technical reflow soldering specification, otherwise no warranty will be sustained.
- Surface discoloration due to reflow processing is permitted.
- Wave soldering is not applicable. Reflow soldering is recommended.
- All products shall be used before the end of the period of 12 months based on the product date-code, if not a 100% solderability can't be ensured.
- The maximum permissible torques must be complied with to prevent mechanical destruction of the elements and PCB.
- Operating current depends on PCB, cable lug and cross section of the cable.
- The connection strength between parts and PCB is determined by product, pad and welding effect
- If the operating current is marked in the manual, the material used for the parts is brass C3604(H59)





Classification Reflow Profile for SMT components:

Classification Reflow Soldering Profile:

Profile Feature		Value
Preheat Temperature Min ($T_{s\ min}$)	$T_{s\ min}$	150 °C
Preheat Temperature Max ($T_{s\ max}$)	$T_{s\ max}$	200 °C
Preheat Time t_s from $T_{s\ min}$ to $T_{s\ max}$	t_s	60-120 seconds
Ramp-up Rate (T_L to T_p)		3 °C/ second max.
Liquidous Temperature (T_L)	T_L	217 °C
Time t_L maintained above T_L	t_L	60-150 seconds
Peak package body temperature		see table
Time within 5°C of actual peak temperature	t_p	20 - 30 seconds
Ramp-down Rate (T_L to T_p)		6 °C/ second max.
Time 25°C to peak temperature		8 minutes max.

Package Classification Reflow Temperature:

Time

Properties	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly I Package Thickness < 1.6 mm	260 °C	260 °C	260 °C
PB-Free Assembly I Package Thickness 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
PB-Free Assembly I Package Thickness > 2.5 mm	250 °C	245 °C	245 °C